100% Material Declaration Data Sheet FGG900

Average Weight: 4.2 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.119328**	**2.84%**
	Silicon	7440-21-3	100.00		0.119328	
Die Attach Material					**0.0105**	**0.25%**
	Silver	7440-22-4	78.00		0.00819	
	Resin	Trade Secret	22.00		0.00231	
Mold Compound					**1.73292**	**41.26%**
	Epoxy Resins	Trade Secret	6.00		0.1039752	
	Phenolic Resins	Trade Secret	6.00		0.1039752	
	Carbon Black	1333-86-4	0.500		0.0086646	
	SiO2 Filler	60676-86-0	84.00		1.4556528	
	Bismuth	7440-69-9	Max. 1.00		0.0173292	
	Metal Hydroxide	Trade Secret	2.50		0.043323	
Laminate					**1.48386**	**35.33%**
	Bismaleimide/Triazine Board	13676-54-5/25722-66-1	17.63		0.261604518	
	Epoxy	29690-82-2	10.59		0.157140774	
	Glass Fiber (GF)	65997-17-3	15.72		0.233262792	
	Copper	7440-50-8	49.01	Metal Layer	0.727239786	
	Nickel	7440-02-0	1.32	Metal Layer	0.019586952	
	Gold	7440-57-5	0.23	Metal Layer	0.003412878	
	Brominated Resin	68541-56-0	5.50	Flame Retardant	0.0816123	
Bond Wire					**0.0189**	**0.45%**
	Gold	7440-57-5	100.00		0.0189	
Solder Balls					**0.83454**	**19.87%**
	Tin	7440-31-5	95.50		0.7969857	
	Silver	7440-22-4	4.00		0.0333816	
	Copper	7440-50-8	0.50		0.0041727	

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Xilinx believes this environmental information to be correct, but cannot guarantee its completeness or accuracy as it is based on data received from sources outside our company.

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
03/27/06	1.0	Initial release.
06/01/06	1.1	100% Material Declaration.
09/22/06	1.2	Updated component descriptions.
09/13/07	1.3	Updated component descriptions and weights

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